

SI2302DS

N-channel enhancement mode field-effect transistor

Rev. 02 — 20 November 2001

Product data

1. Description

N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS^{TM1} technology.

Product availability:

SI2302DS in SOT23.

2. Features

- TrenchMOSTM technology
- Very fast switching
- Logic level compatible
- Subminiature surface mount package.

3. Applications

- Battery management
- High speed switch
- Low power DC to DC converter.

4. Pinning information

Table 1: Pinning - SOT23, simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)	<p>Top view MSB003</p>	<p>MBB076</p>
2	source (s)		
3	drain (d)		

SOT23

1. TrenchMOS is a trademark of Koninklijke Philips Electronics N.V.



5. Quick reference data

Table 2: Quick reference data

Symbol	Parameter	Conditions	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 150 °C	–	20	V
I_D	drain current (DC)	$T_{sp} = 25$ °C; $V_{GS} = 4.5$ V	–	2.5	A
P_{tot}	total power dissipation	$T_{sp} = 25$ °C	–	0.83	W
T_j	junction temperature		–	150	°C
R_{DSon}	drain-source on-state resistance	$V_{GS} = 4.5$ V; $I_D = 3.6$ A	56	85	mΩ
		$V_{GS} = 2.5$ V; $I_D = 3.1$ A	77	115	mΩ

6. Limiting values

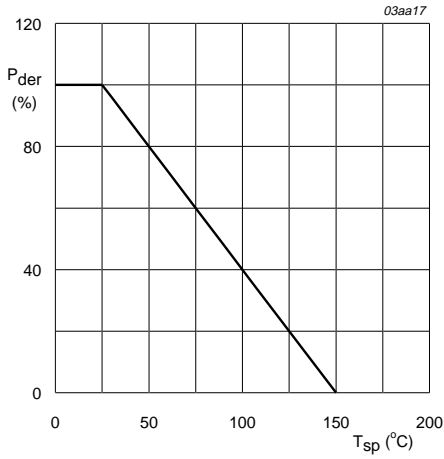
Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 150 °C	–	20	V
V_{GS}	gate-source voltage (DC)		–	±8	V
I_D	drain current (DC)	$T_{sp} = 25$ °C; $V_{GS} = 4.5$ V; Figure 2 and 3	–	2.5	A
		$T_{sp} = 70$ °C; $V_{GS} = 4.5$ V; Figure 2	–	2	A
I_{DM}	peak drain current	$T_{sp} = 25$ °C; pulsed; $t_p \leq 10$ μs; Figure 3	–	10	A
P_{tot}	total power dissipation	$T_{sp} = 25$ °C; Figure 1	–	0.83	W
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–65	+150	°C

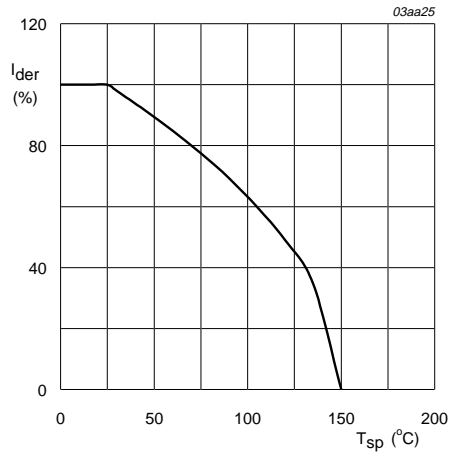
Source-drain diode

I_S	source (diode forward) current (DC)	$T_{sp} = 25$ °C	–	0.7	A
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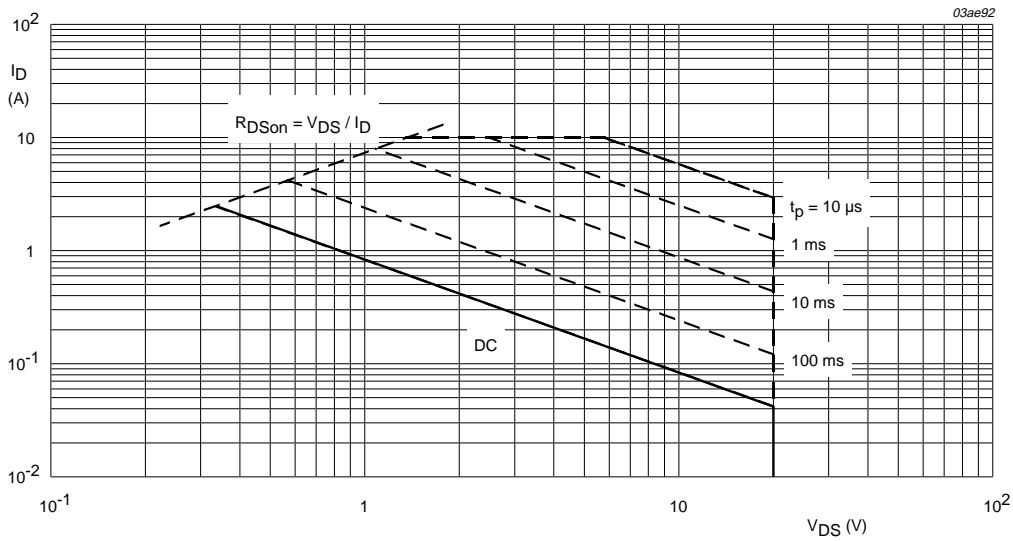
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of solder point temperature.



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of solder point temperature.



T_{sp} = 25 °C; I_{DM} is single pulse.

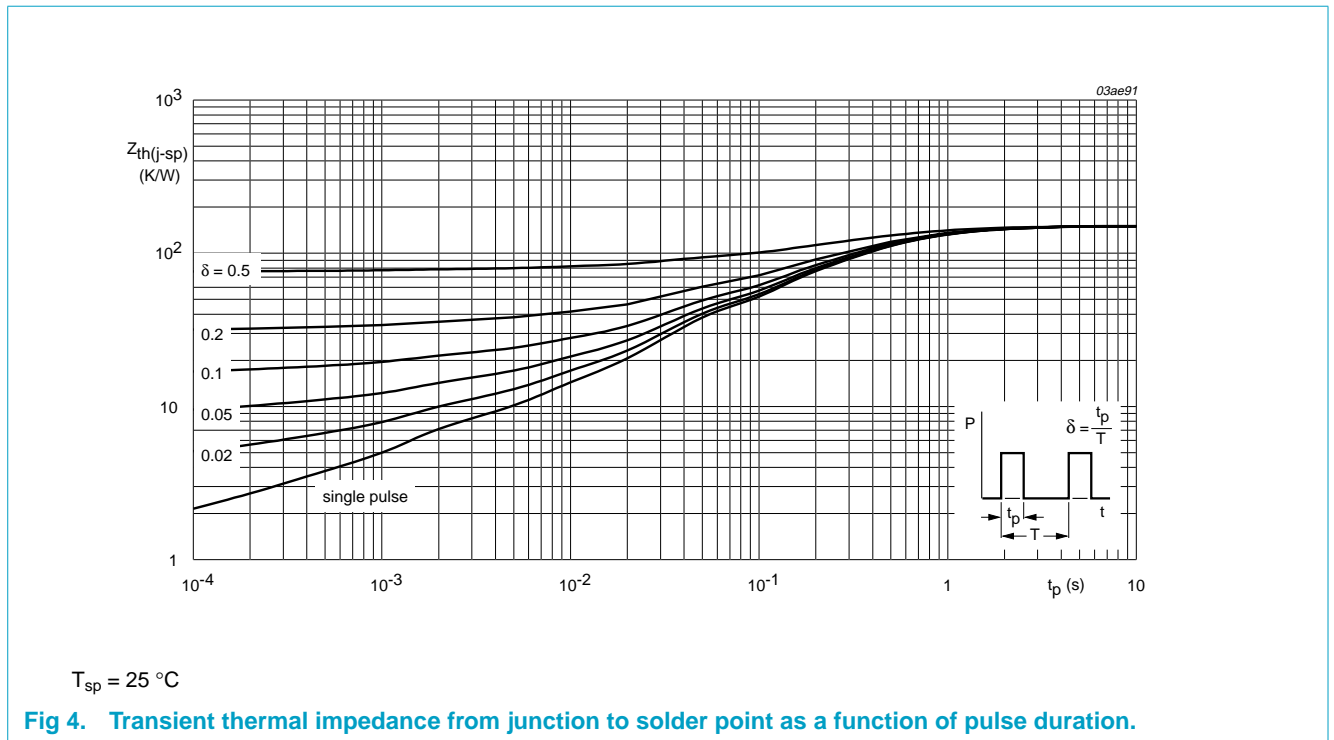
Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

7. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	mounted on a metal clad substrate; Figure 4	150	K/W

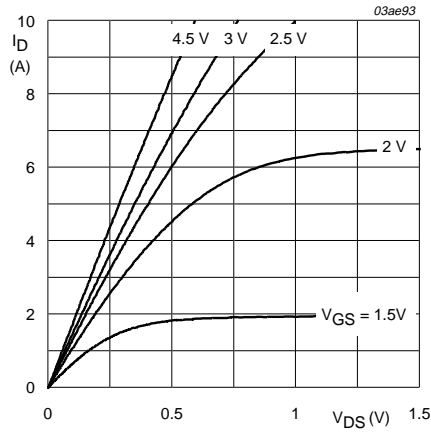
7.1 Transient thermal impedance



8. Characteristics

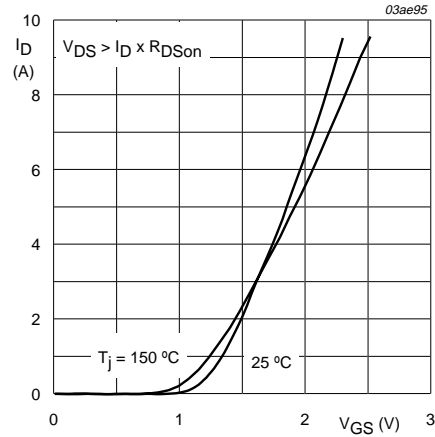
Table 5: Characteristics
T_j = 25 °C unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 10 μA; V _{GS} = 0 V	20	–	–	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} = V _{GS} ; Figure 9	0.65	–	–	V
I _{DSS}	drain-source leakage current	V _{DS} = 20 V; V _{GS} = 0 V				
		T _j = 25 °C	–	0.01	1.0	μA
		T _j = 55 °C	–	–	10	μA
I _{GSS}	gate-source leakage current	V _{GS} = ±8 V; V _{DS} = 0 V	–	10	100	nA
R _{DS(on)}	drain-source on-state resistance	V _{GS} = 4.5 V; I _D = 3.6 A; Figure 7 and 8	–	56	85	mΩ
		V _{GS} = 2.5 V; I _D = 3.1 A; Figure 7 and 8	–	77	115	mΩ
Dynamic characteristics						
g _{fs}	forward transconductance	V _{DS} = 5 V; I _D = 3.6 A	–	8	–	S
Q _{g(tot)}	total gate charge	V _{DD} = 10 V; V _{GS} = 4.5 V; I _D = 3.6 A; Figure 13	–	5.4	10	nC
Q _{gs}	gate-source charge		–	0.65	–	nC
Q _{gd}	gate-drain (Miller) charge		–	1.6	–	nC
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 10 V; f = 1 MHz; Figure 11	–	230	–	pF
C _{oss}	output capacitance		–	125	–	pF
C _{rss}	reverse transfer capacitance		–	80	–	pF
t _{d(on)}	turn-on delay time	V _{DD} = 10 V; R _L = 5.5 Ω; V _{GS} = 4.5 V; R _G = 6 Ω	–	12	20	ns
t _r	rise time		–	23	35	ns
t _{d(off)}	turn-off delay time		–	50	100	ns
t _f	fall time		–	34	50	ns
Source-drain diode						
V _{SD}	source-drain (diode forward) voltage	I _S = 1.6 A; V _{GS} = 0 V; Figure 12	–	0.8	1.2	V



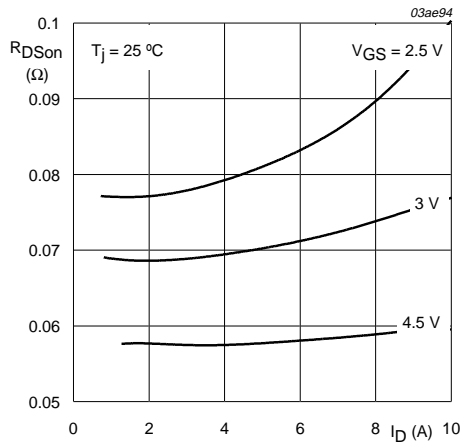
$T_j = 25\text{ }^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



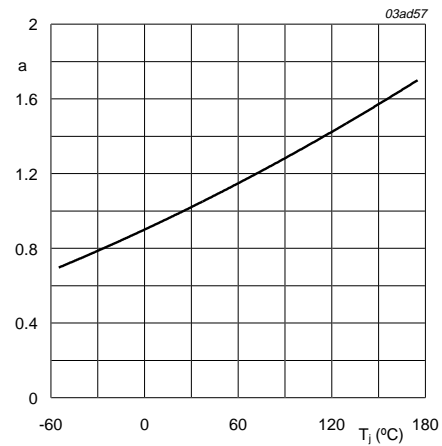
$T_j = 25\text{ }^\circ\text{C}$ and $150\text{ }^\circ\text{C}$; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



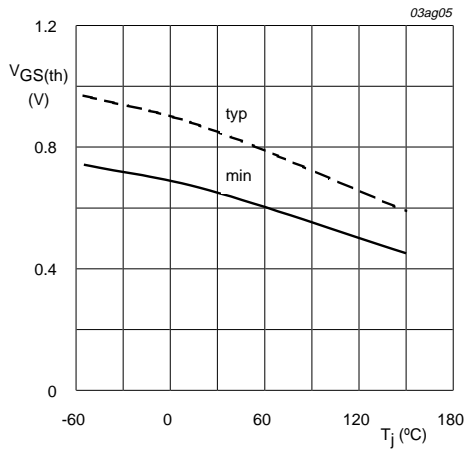
$T_j = 25\text{ }^\circ\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



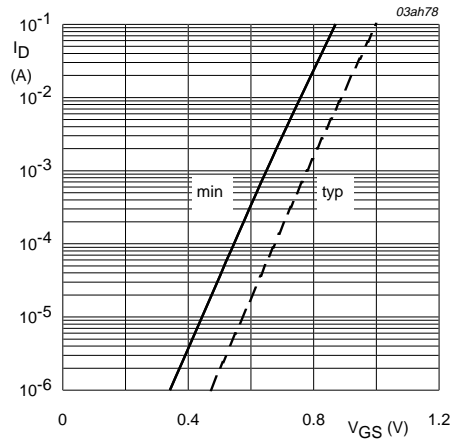
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



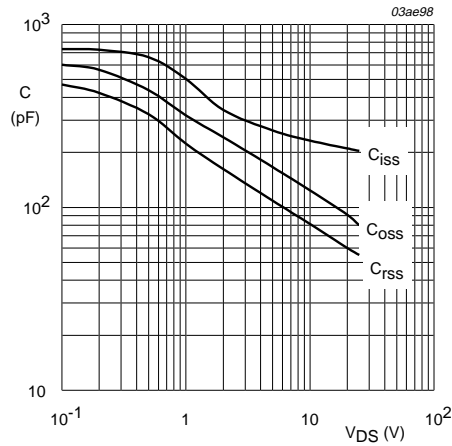
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



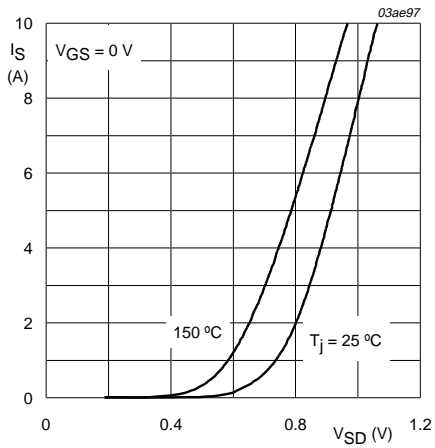
$T_j = 25 \text{ }^\circ\text{C}; V_{DS} = 5 \text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



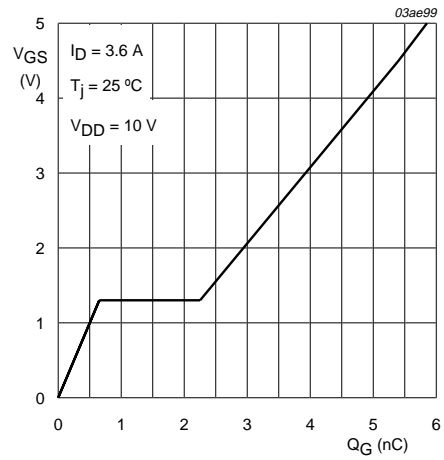
$V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_j = 25$ °C and 150 °C; $V_{GS} = 0$ V

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 3.6$ A; $V_{DD} = 10$ V

Fig 13. Gate-source voltage as a function of gate charge; typical values.

9. Package outline

Plastic surface mounted package; 3 leads

SOT23

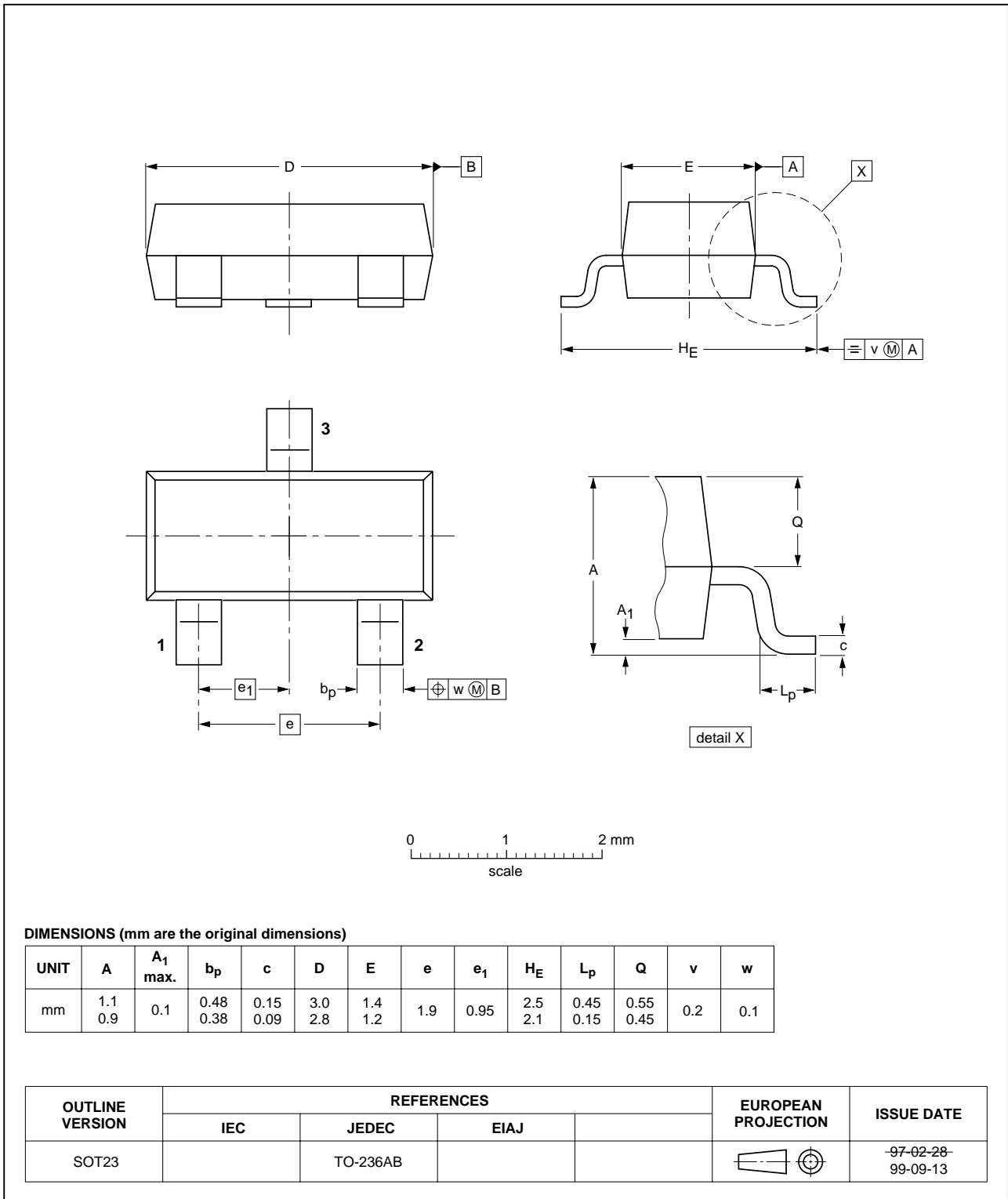


Fig 14. SOT23.

10. Revision history

Table 6: Revision history

Rev	Date	CPCN	Description
02	20011120	-	Includes product data; second version; supersedes initial version 03 september 2001. <ul style="list-style-type: none">• Table 5 "Characteristics" Correction to $V_{GS(th)}$ conditions.• Figure 9 Correction to curves.• Figure 10 Correction to curves.
01	20010903	-	Product specification; initial version.

11. Data sheet status

Data sheet status ^[1]	Product status ^[2]	Definition
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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